

Appl. No. 10/055,301

Amdt. Dated August 15, 2005

Reply to Office Action of May 13, 2005

Amendments to the Specification:

Please add the following new paragraph immediately before the paragraph at line 9, page 5 beginning with "It has been determined that the ZrN finish." This corresponds to paragraph 0015 of the published US 2003/0139106.

Briefly, in the sputter ion physical vapor deposition process the refractory metal, such as titanium or zirconium target, which is the cathode, and the substrate are placed in a vacuum chamber. The air in the chamber is evacuated to produce vacuum conditions in the chamber. An inert gas, such as argon, is introduced into the chamber. The gas particles are ionized and are accelerated to the target to dislodge titanium or zirconium atoms. The dislodged target material is then typically deposited as a coating film on the substrate.